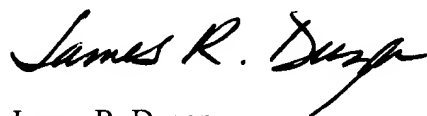


**REMARKS**

No new matter has been added. The Applicant requests entry of the foregoing amendment prior to examination of the application on the merits.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "James R. Duzan". The signature is fluid and cursive, with the first name "James" and last name "Duzan" clearly legible.

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Date: May 30, 2001

JRD/dn

**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

1. (Amended) A semiconductor assembly comprising:  
a substrate having a surface;  
a semiconductor die having a plurality of edges, having an active surface having a plurality of bond pads thereon located adjacent at least two edges of the plurality of edges, and having a back side surface, the semiconductor die having at least a portion of the back side surface adhesively attached to at least a portion of the surface of the substrate;  
an encapsulation material covering a portion of the surface of the substrate, the plurality of edges of the semiconductor die, and at least one bond pad of the plurality of bond pads located [on]adjacent at least two edges of the semiconductor die; and  
a heat sink attached to a portion of the active surface of the semiconductor die.

6. (Amended) A semiconductor assembly comprising:  
a substrate having a plurality of electrical connections on a portion of [the]a surface thereof;  
at least one semiconductor die having a plurality of bond pads on a first portion of [the]an active surface thereof and having a back side surface, a portion of the back side surface adhesively attached to a portion of the surface of the substrate;  
a plurality of wire bonds connecting at least a portion of the plurality of bond pads of the at least one semiconductor die to at least a portion of the plurality of electrical connections of the substrate;  
an encapsulant material covering a portion of the surface of the substrate, the plurality of bond pads on the active surface of the at least one semiconductor die, a portion of the active surface of the at least one semiconductor die, and the plurality of wire bonds; and  
a heat sink attached to a second portion of the active surface of the at least one semiconductor die.

8. (Amended) A semiconductor assembly comprising:

- a substrate having a surface having a plurality of circuits on a portion thereof;
- a semiconductor die having a plurality of bond pads located on a first portion of [the]an active surface thereof and having a back side surface;
- a plurality of solder balls connecting at least a portion of the plurality of bond pads of the semiconductor die to at least a portion of the plurality of circuits of the substrate;
- a metal filled cross-linked silicone compliant adhesive filled gel elastomer contacting a portion of the back side surface of the semiconductor die; and
- a heat sink cap having a portion thereof in contact with a portion of the metal filled cross-linked silicone compliant adhesive filled gel elastomer, the heat sink cap covering the metal filled cross-linked silicone compliant adhesive filled gel elastomer, the semiconductor die, the plurality of solder balls, and at least a portion of the substrate.